



Docket No.: A8319.0014/P014
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Takeyuki Itabashi et al.

Application No.: 10/076,536

Art Unit: 1762

Filed: February 19, 2002

Examiner: Not Yet Assigned

For: ELECTROLESS COPPER PLATING
SOLUTION, ELECTROLESS COPPER
PLATING PROCESS AND PRODUCTION
PROCESS OF CIRCUIT BOARD

AMENDMENT AFTER FINAL ACTION (37 C.F.R. SECTION 1.116)

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated January 15, 2004 (Paper No. 20040112), finally rejecting claims 2-9, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.